# Thermal Flowable Gap Putty Multicomp





## Description

Formable gap putty (FGP) work by being dispensed into the available gap. When applied to an irregular surface between the heat source and heat sink, the material will stay in the required area. This improves contact between the surfaces, completely filling air gaps and voids and thereby increasing heat transfer.

#### Features

- · No flowing when set
- · Maintains superior contact with components
- · Convenient for usage
- · High thermal conductivity

## Applications

- Communications equipment
- · Automotive electronics
- · Mainframe and small office networking
- · Cooling modules

#### **Properties**

Characteristic	Value	Test Method
Colour	Pink	Visual
Thermal Conductivity	3W/m.K	ISO 22007-2
Thermal Impedance	0.025°C-in <sup>2</sup> /W	ASTM-D5470
Operating Temperature	-40°C to +200°C	EN344
Extrusion Rate	20	-

## Part Number Table

Description	Part Number
Thermal Flowable Gap Putty, White, 3W/mK, 30ml	MPGCS-030-FGP-30cc

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